

PEMH19; PUMH19

NPN/NPN resistor-equipped transistors;
R1 = 22 k Ω , R2 = open

Rev. 02 — 2 May 2005

Product data sheet

1. Product profile

1.1 General description

NPN/NPN Resistor-Equipped Transistors (RET).

Table 1: Product overview

| Type number | Package | | NPN/PNP complement | PNP/PNP complement |
|-------------|---------|-------|--------------------|--------------------|
| | Philips | JEITA | | |
| PEMH19 | SOT666 | - | PEMD19 | PEMB19 |
| PUMH19 | SOT363 | SC-88 | PUMD19 | PUMB19 |

1.2 Features

- Built-in bias resistor
- Simplifies circuit design
- Reduces component count
- Reduces pick and place costs

1.3 Applications

- Low current peripheral driver
- Control of IC inputs
- Replaces general-purpose transistors in digital applications

1.4 Quick reference data

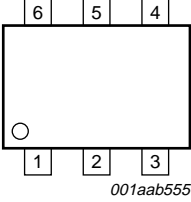
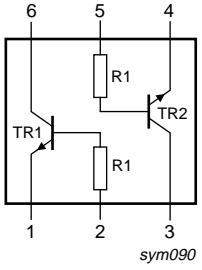
Table 2: Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|------------------|---------------------------|------------|------|-----|------|------------|
| V _{CEO} | collector-emitter voltage | open base | - | - | 50 | V |
| I _O | output current (DC) | | - | - | 100 | mA |
| R1 | bias resistor 1 (input) | | 15.4 | 22 | 28.6 | k Ω |

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2. Pinning information

Table 3: Pinning

| Pin | Description | Simplified outline | Symbol |
|-----|------------------------|--|---|
| 1 | GND (emitter) TR1 |  <p>001aab555</p> |  <p>sym090</p> |
| 2 | input (base) TR1 | | |
| 3 | output (collector) TR2 | | |
| 4 | GND (emitter) TR2 | | |
| 5 | input (base) TR2 | | |
| 6 | output (collector) TR1 | | |

3. Ordering information

Table 4: Ordering information

| Type number | Package | | |
|-------------|---------|--|---------|
| | Name | Description | Version |
| PEMH19 | - | plastic surface mounted package; 6 leads | SOT666 |
| PUMH19 | SC-88 | plastic surface mounted package; 6 leads | SOT363 |

4. Marking

Table 5: Marking codes

| Type number | Marking code [1] |
|-------------|------------------|
| PEMH19 | 6F |
| PUMH19 | H6* |

[1] * = -: made in Hong Kong
 * = p: made in Hong Kong
 * = t: made in Malaysia
 * = W: made in China

5. Limiting values

Table 6: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit | | |
|-----------------------|---------------------------|--------------------------|--------|--------|------|-----|----|
| Per transistor | | | | | | | |
| V _{CBO} | collector-base voltage | open emitter | - | 50 | V | | |
| V _{CEO} | collector-emitter voltage | open base | - | 50 | V | | |
| V _{EBO} | emitter-base voltage | open collector | - | 5 | V | | |
| I _O | output current (DC) | | - | 100 | mA | | |
| I _{CM} | peak collector current | | - | 100 | mA | | |
| P _{tot} | total power dissipation | T _{amb} ≤ 25 °C | | | | | |
| | | | SOT363 | [1] | - | 200 | mW |
| | | | SOT666 | [1][2] | - | 200 | mW |
| T _{stg} | storage temperature | | -65 | +150 | °C | | |
| T _j | junction temperature | | - | 150 | °C | | |
| T _{amb} | ambient temperature | | -65 | +150 | °C | | |
| Per device | | | | | | | |
| P _{tot} | total power dissipation | T _{amb} ≤ 25 °C | | | | | |
| | | | SOT363 | [1] | - | 300 | mW |
| | | | SOT666 | [1][2] | - | 300 | mW |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

6. Thermal characteristics

Table 7: Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit | | |
|-----------------------|---|-------------|--------|--------|-----|------|-----|-----|
| Per transistor | | | | | | | | |
| R _{th(j-a)} | thermal resistance from junction to ambient | in free air | | | | | | |
| | | | SOT363 | [1] | - | - | 625 | K/W |
| | | | SOT666 | [1][2] | - | - | 625 | K/W |
| Per device | | | | | | | | |
| R _{th(j-a)} | thermal resistance from junction to ambient | in free air | | | | | | |
| | | | SOT363 | [1] | - | - | 416 | K/W |
| | | | SOT666 | [1][2] | - | - | 416 | K/W |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

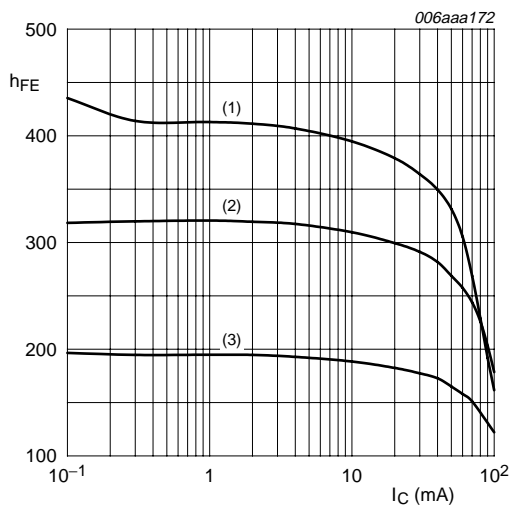
[2] Reflow soldering is the only recommended soldering method.

7. Characteristics

Table 8: Characteristics

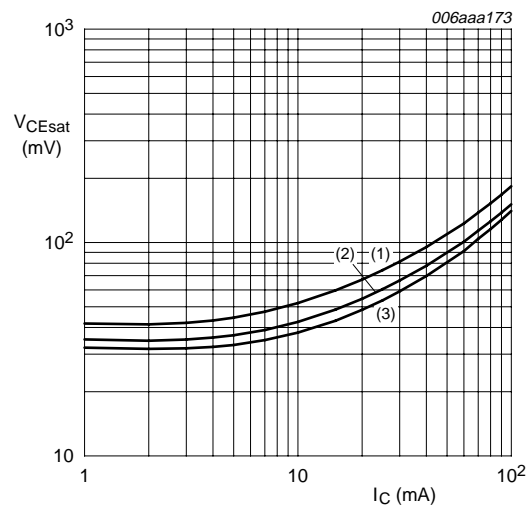
T_{amb} = 25 °C unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------------------|--------------------------------------|--|------|-----|------|------|
| Per transistor | | | | | | |
| I _{CBO} | collector-base cut-off current | V _{CB} = 50 V; I _E = 0 A | - | - | 100 | nA |
| I _{CEO} | collector-emitter cut-off current | V _{CE} = 30 V; I _B = 0 A | - | - | 1 | μA |
| | | V _{CE} = 30 V; I _B = 0 A; T _j = 150 °C | - | - | 50 | μA |
| I _{EBO} | emitter-base cut-off current | V _{EB} = 5 V; I _C = 0 A | - | - | 100 | nA |
| h _{FE} | DC current gain | V _{CE} = 5 V; I _C = 1 mA | 100 | - | - | |
| V _{CEsat} | collector-emitter saturation voltage | I _C = 10 mA; I _B = 0.5 mA | - | - | 150 | mV |
| R1 | bias resistor 1 (input) | | 15.4 | 22 | 28.6 | kΩ |
| C _c | collector capacitance | V _{CB} = 10 V; I _E = i _e = 0 A; f = 1 MHz | - | - | 2.5 | pF |



V_{CE} = 5 V
 (1) T_{amb} = 100 °C
 (2) T_{amb} = 25 °C
 (3) T_{amb} = -40 °C

Fig 1. DC current gain as a function of collector current; typical values



I_C/I_B = 20
 (1) T_{amb} = 100 °C
 (2) T_{amb} = 25 °C
 (3) T_{amb} = -40 °C

Fig 2. Collector-emitter saturation voltage as a function of collector current; typical values

8. Package outline

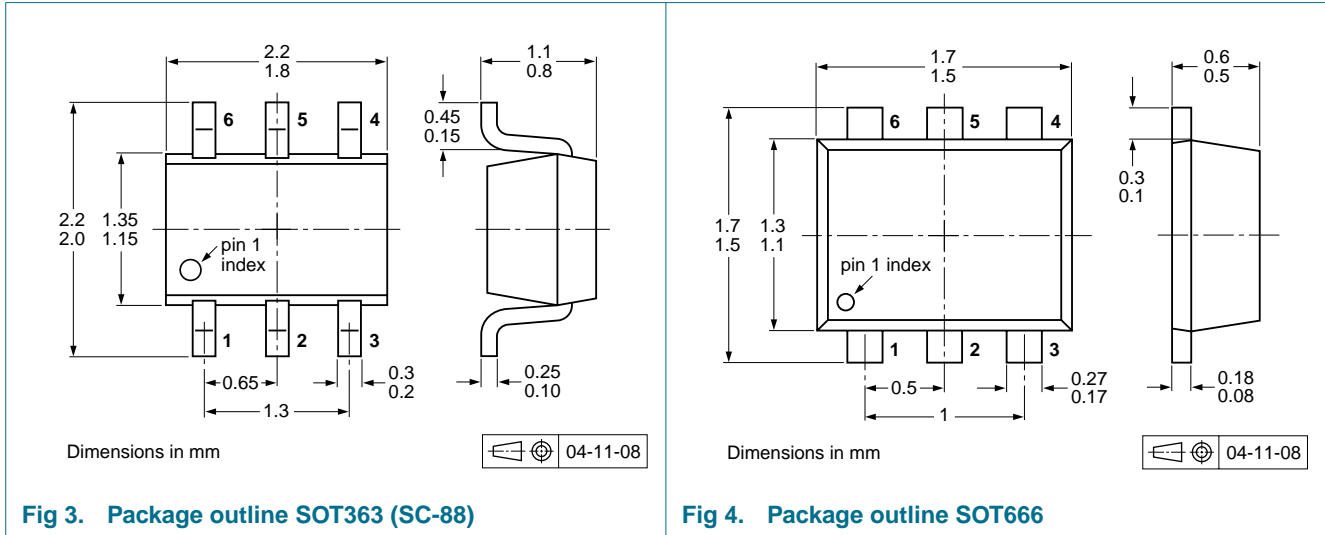


Fig 3. Package outline SOT363 (SC-88)

Fig 4. Package outline SOT666

9. Packing information

Table 9: Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code. [1]

| Type number | Package | Description | Packing quantity | | | |
|-------------|---------|--|------------------|------|------|-------|
| | | | 3000 | 4000 | 8000 | 10000 |
| PEMH19 | SOT666 | 2 mm pitch, 8 mm tape and reel | - | - | -315 | - |
| | | 4 mm pitch, 8 mm tape and reel | - | -115 | - | - |
| PUMH19 | SOT363 | 4 mm pitch, 8 mm tape and reel; T1 [2] | -115 | - | - | -135 |
| | | 4 mm pitch, 8 mm tape and reel; T2 [3] | -125 | - | - | -165 |

[1] For further information and the availability of packing methods, see Section 15.

[2] T1: normal taping

[3] T2: reverse taping

10. Revision history

Table 10: Revision history

| Document ID | Release date | Data sheet status | Change notice | Doc. number | Supersedes |
|-----------------|--------------|-----------------------|---------------|----------------|---|
| PEMH19_PUMH19_2 | 20050502 | Product data sheet | - | 9397 750 14462 | PUMH19_1 |
| Modifications: | | | | | |
| | | | | | <ul style="list-style-type: none">• The format of this data sheet has been redesigned to comply with the new presentation and information standard of Philips Semiconductors.• Type PEMH19 added• Figure 1 and 2: added• Section 9 "Packing information": added• Section 14 "Trademarks": added |
| PUMH19_1 | 20031016 | Product specification | - | 9397 750 11893 | - |

11. Data sheet status

| Level | Data sheet status ^[1] | Product status ^{[2] [3]} | Definition |
|-------|----------------------------------|-----------------------------------|--|
| I | Objective data | Development | This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice. |
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[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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